MURF1060CT

Rev.E Mar.-2016

蓝箭电子
BLUE ROCKET ELECTRONICS

DATA SHEET

/ Descriptions

TO-220F

Ultrafast Recovery Diode in a TO-220F Plastic Package.

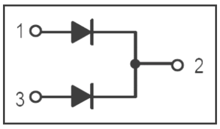
/ Features

Silicon epitaxial process to produce ultrafast recovery diode with low reverse leakage current and high reliability.

/ Applications

For high frequency, high voltage, high current rectifier diode, freewheeling diode

/ Equivalent Circuit



/ Pinning

PIN1	Anode	PIN2	Cathode	PIN 3	Anode

/ h_{FE} Classifications & Marking

See Marking Instructions

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	600	V
RMS Reverse Voltage	V_{RMS}	420	V
DC Blocking Voltage	V_{DC}	600	V
Forward Current	I_F	2 × 5	A
Peak forward surge current	I_{FSM}	100	A
Typical Thermal Resistance Junction to Case	$R_{\theta Jc}$	4	/W
Junction Temperature Range	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

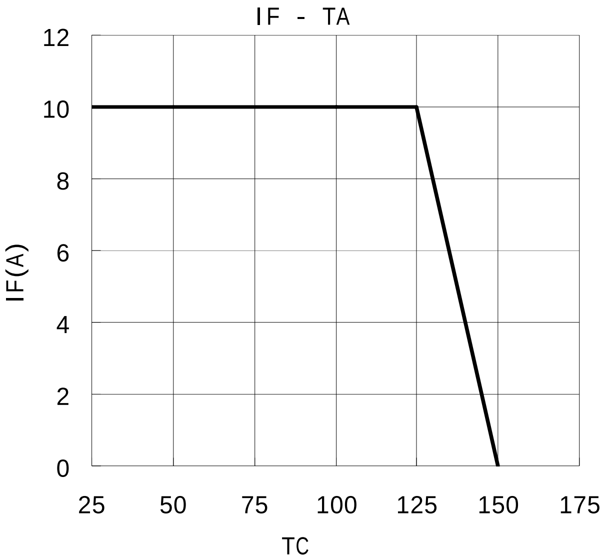
/ Electrical Characteristics(Ta=25)

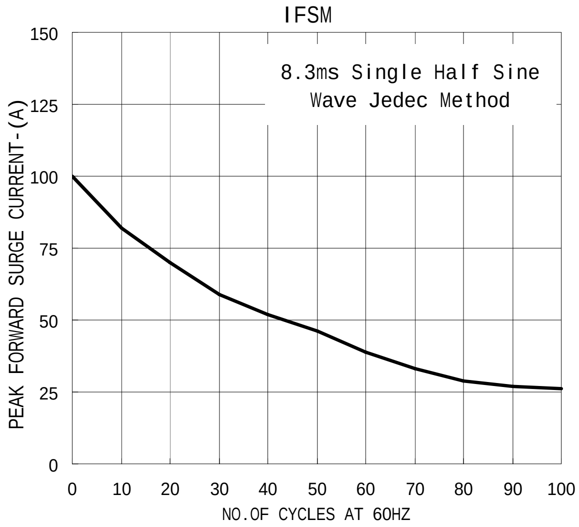
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	V_R	I_R=1mA	600			V
Forward Voltage	V_F	I_F=1A T_C=25		0.91	1.05	V
		I_F=1A T_C=125		0.74	0.95	
		I_F=5A T_C=25		1.15	1.5	
		I_F=5A T_C=125		1.0	1.2	
Instantaneous Reverse Current	I_R Note 1	V_R=600V T_a=25			10	μA
		V_R=600V T_a=125			500	
Reverse Recovery Time	t_{rr}	I_F=0.5A I_R=1.0A I_{RR}=0.25A			50	ns

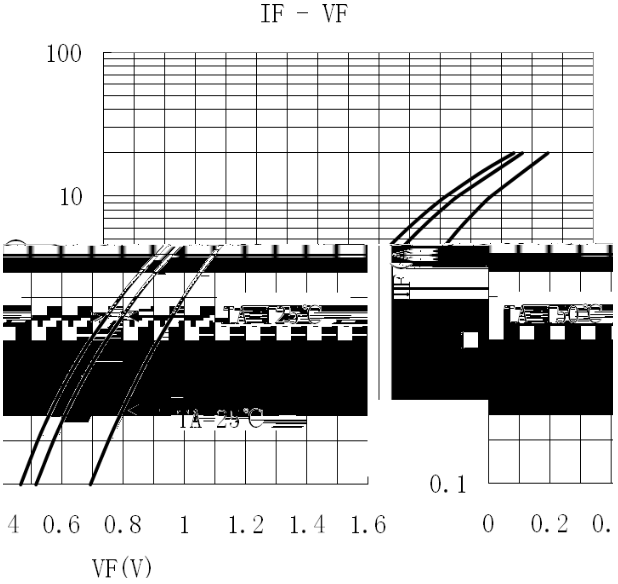
/Notes

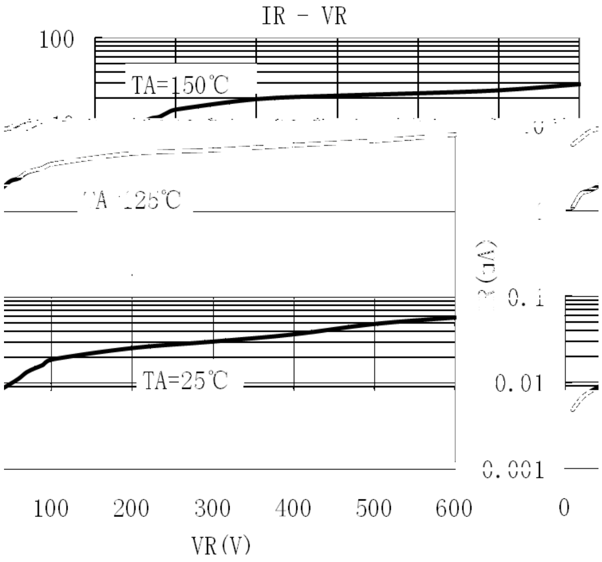
1. /Short duration pulse test used to minimize self-heating effect.
2. / Unless otherwise noted, values for the parameters of a single chip

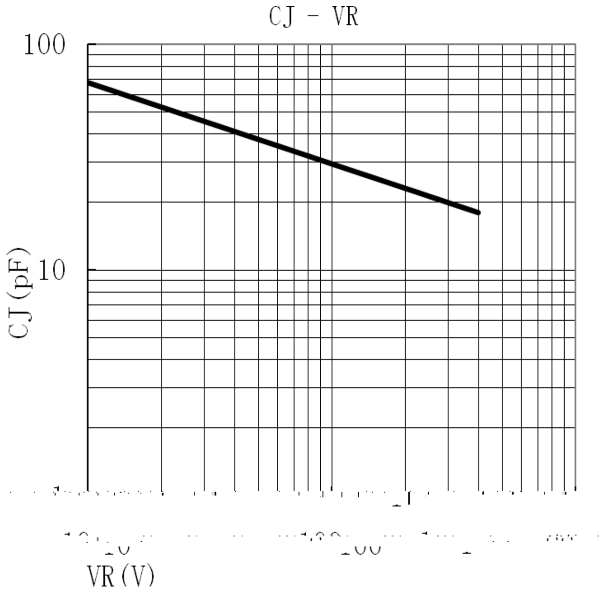
/ Electrical Characteristic Curve



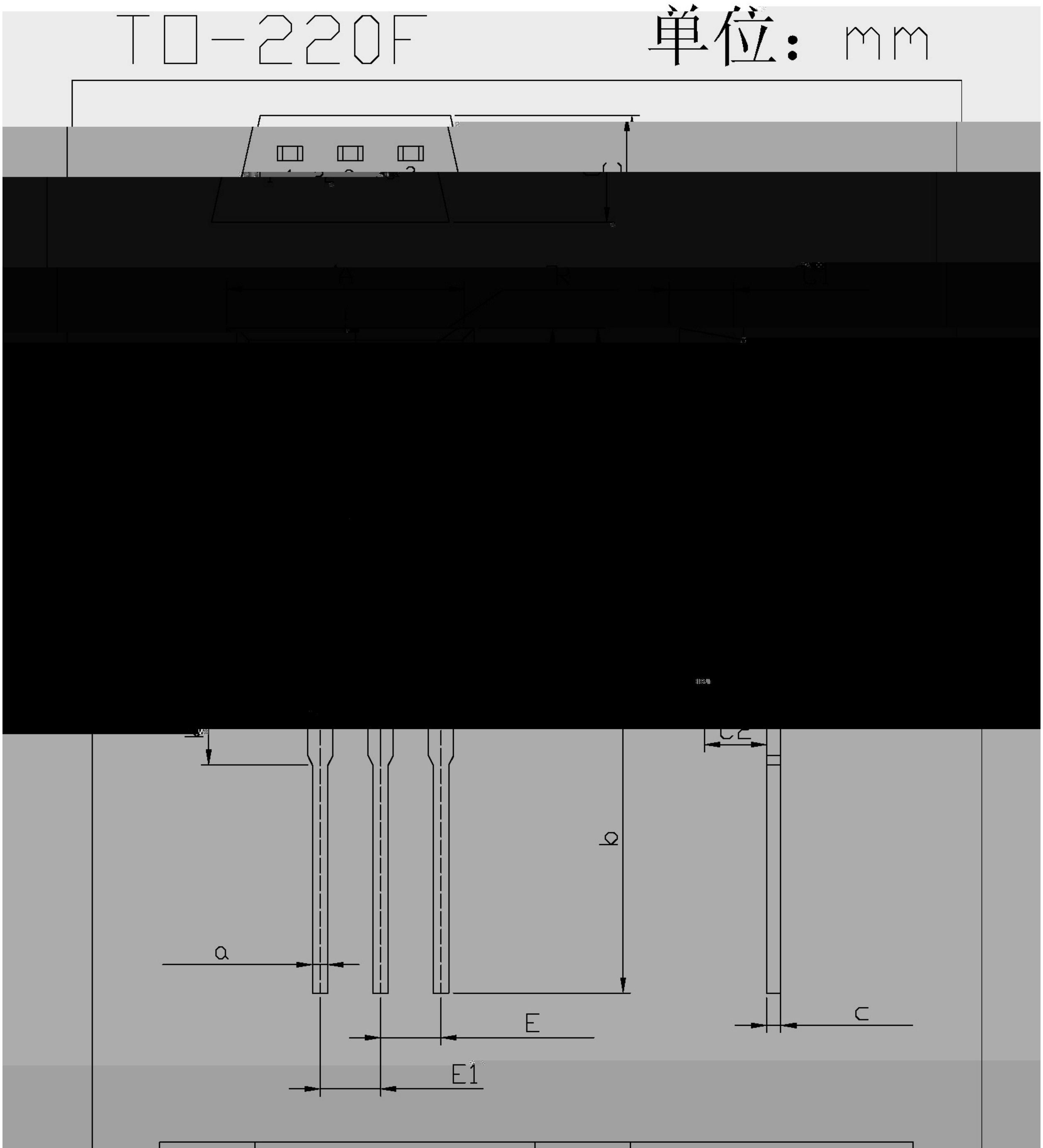






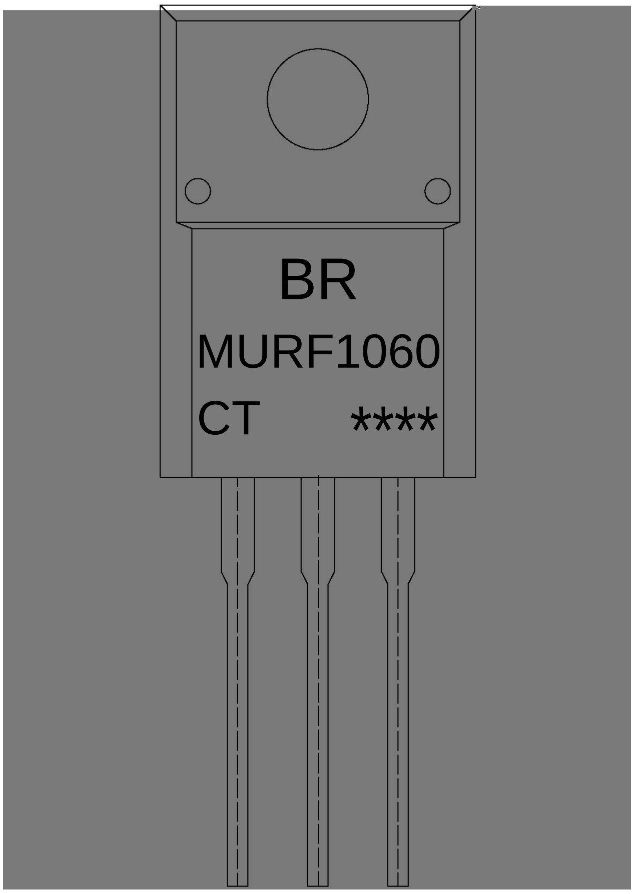


/ Package Dimensions



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
C	4.3	4.7	b1	2.9	3.9
A	9.7	10.3	a	0.55	0.75
B	14.7	15.3	E	2.29	2.79

/ Marking Instructions



BR

MURF1060

CT:

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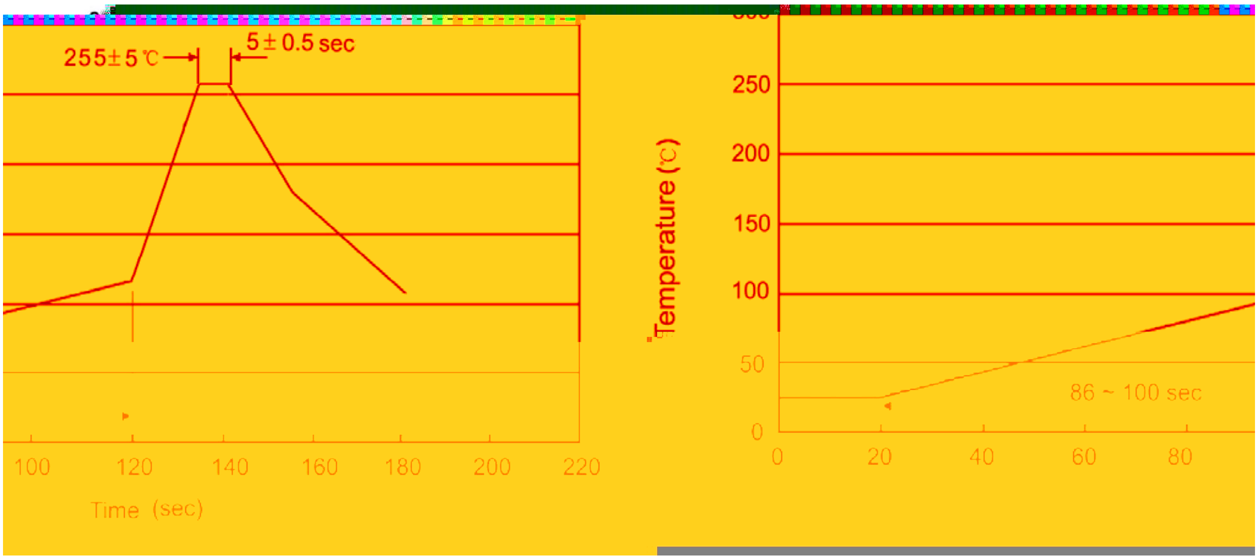
Note:

BR:	Company Code
MURF1060	Product Type.
CT:	Internal Structure
****:	Lot No. Code, code change with Lot No.

(　　) / Temperature Profile for Dip Soldering(Pb-Free)



Note:

1　　25　150　　60　90sec;	1.Preheating:25~150　, Time:60~90sec.
2　　255±5　　5±0.5sec;	2.Peak Temp.:255±5　, Duration:5±0.5sec.
3　　2　10　/sec.	3. Cooling Speed: 2~10　/sec.

/ Resistance to Soldering Heat Test Conditions

270±5　　10±1 sec.　　Temp.:270±5　　Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units				Dimension (unit mm^3)
	Units/Bag /	Bags/Inner Box /	Units/Inner Box /	In±o016k9016kOu016e4x	